



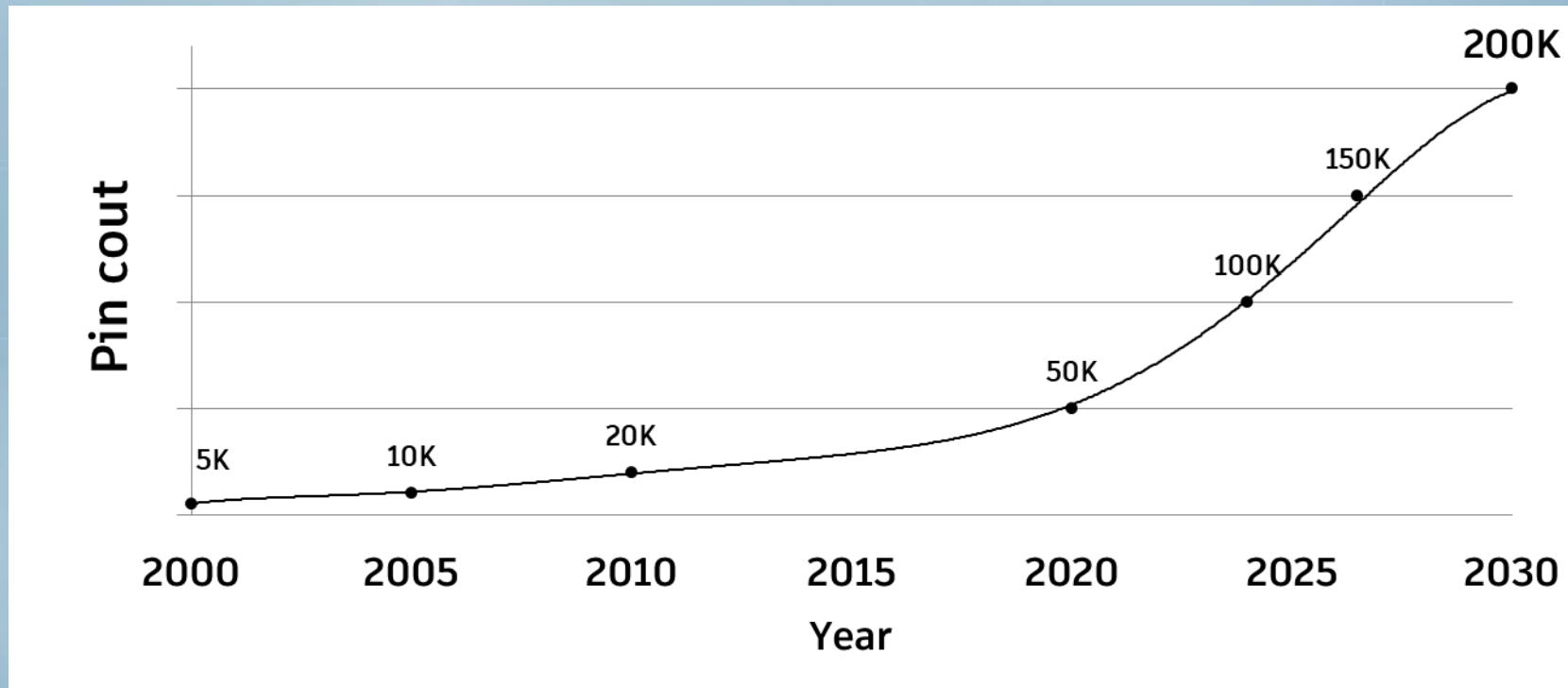
100+K ULTRA HIGH PIN COUNT PROBE CARD



Zach HSIEH
(MPI Corporation - Taiwan)

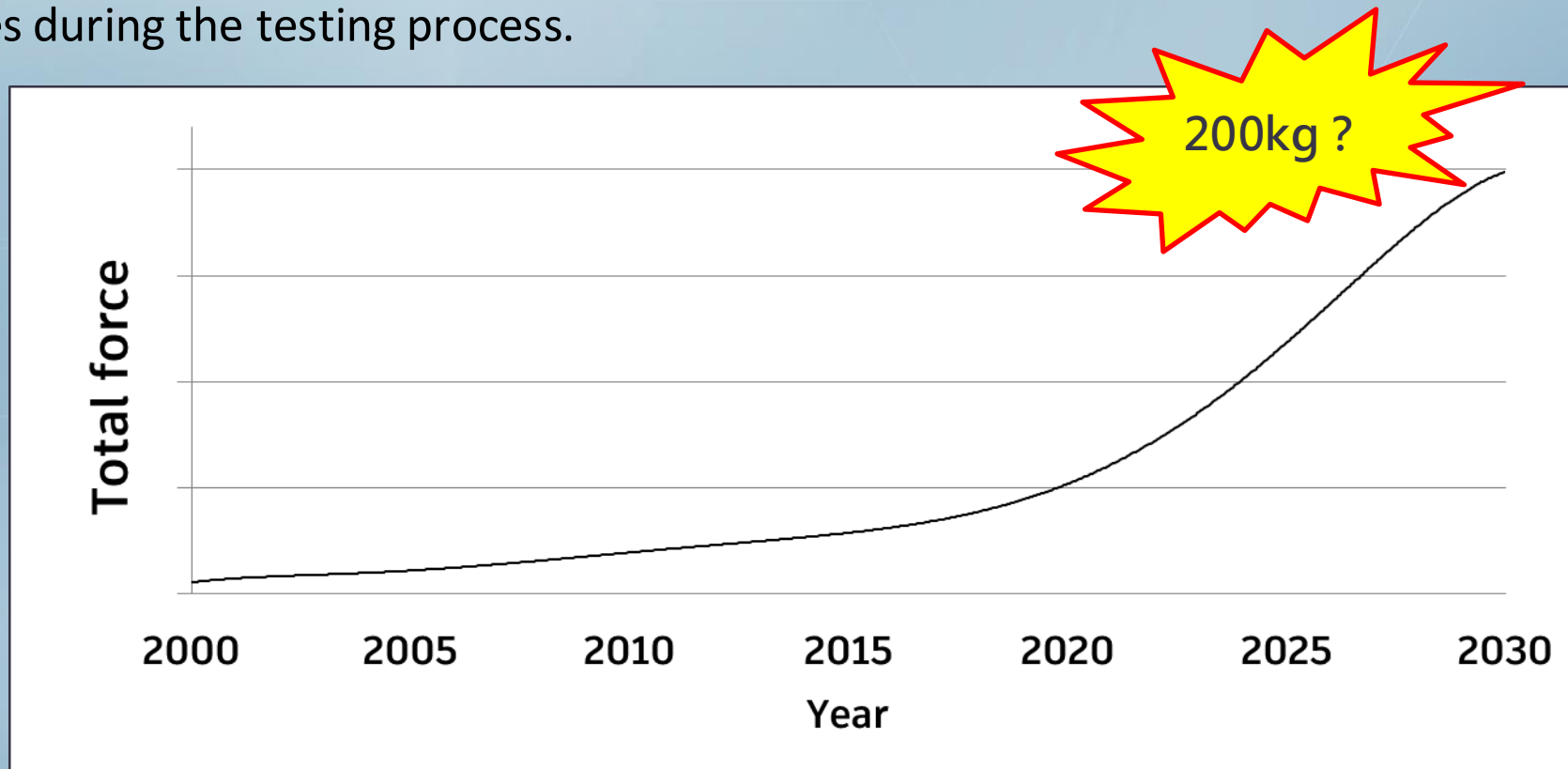
Market Status

With the semiconductor industry's increasing demand for more efficient testing, there has been a clear upward trend in the number of concurrent tests on probe cards. Consequently, the pin count has risen year by year, with a particularly rapid increase in recent years. By 2025, the demand is projected to reach 100,000 pins for testing.



Market Status

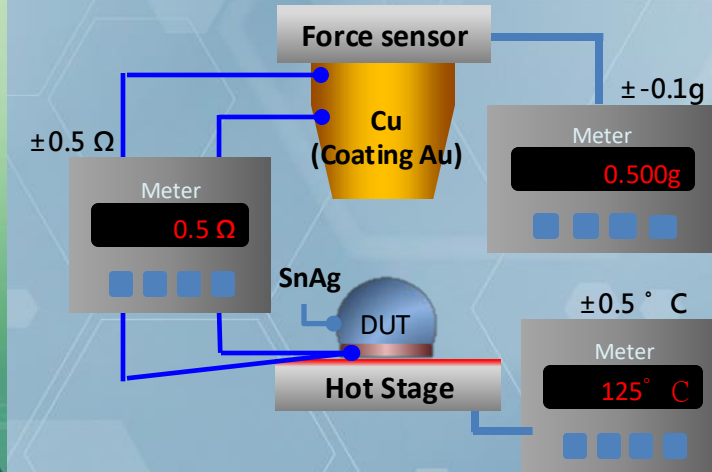
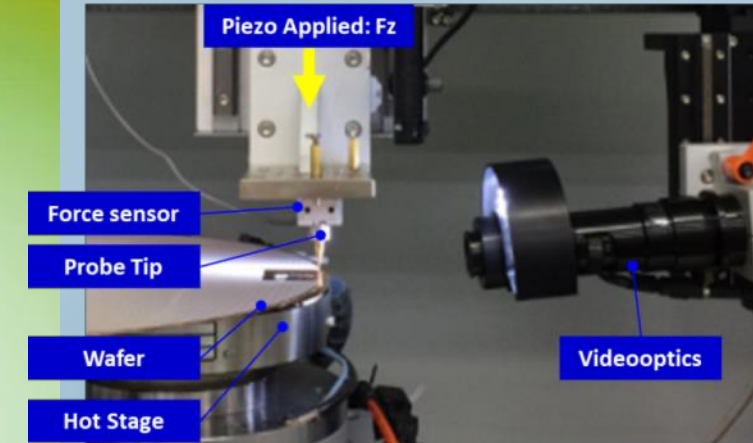
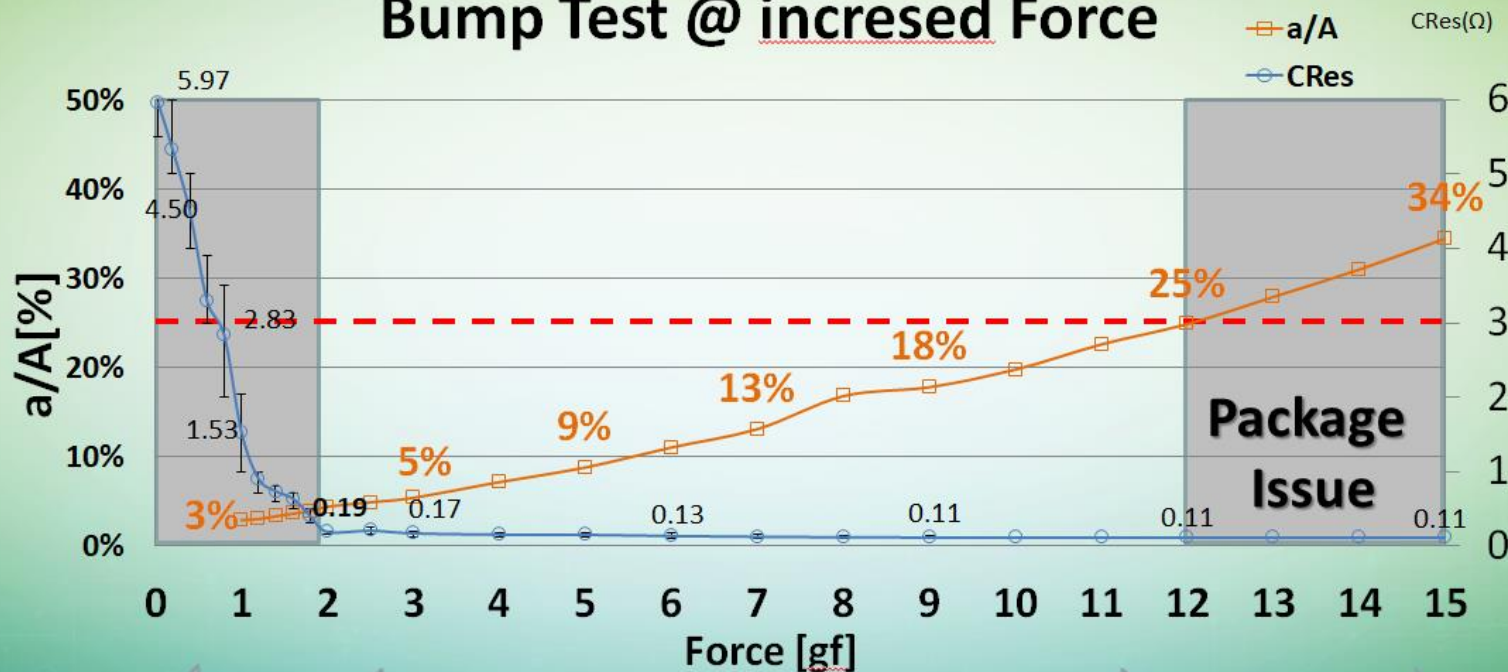
As the pin count rises, the total force exerted across the probe card escalates correspondingly. Each individual pin contributes to the cumulative force, which means that probe cards with higher pin counts, particularly those seen in advanced and future designs, will face the challenge of managing significantly greater forces during the testing process.



How to define the force range of the specific Bump

How to define the force range with application

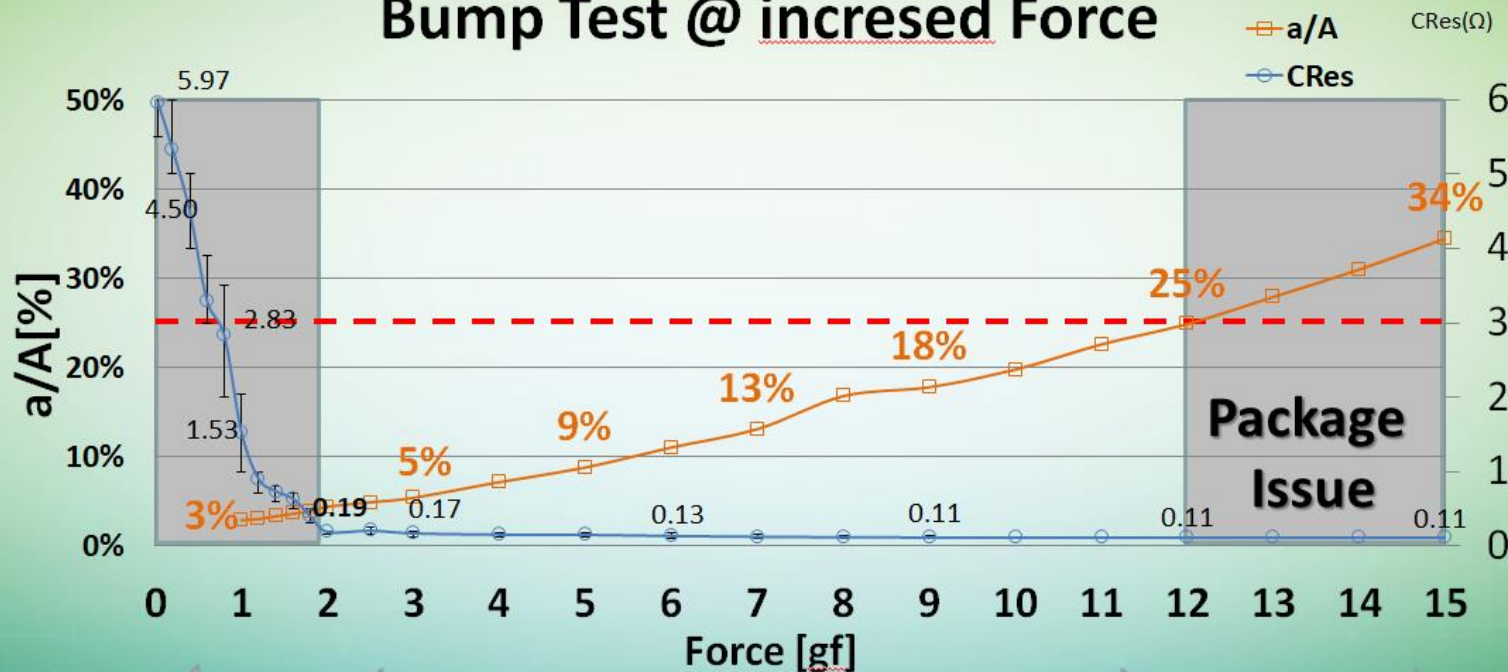
Bump Test @ increased Force



How to define the force range of 100K+ Bumps

How to define the force range with application

Bump Test @ increased Force

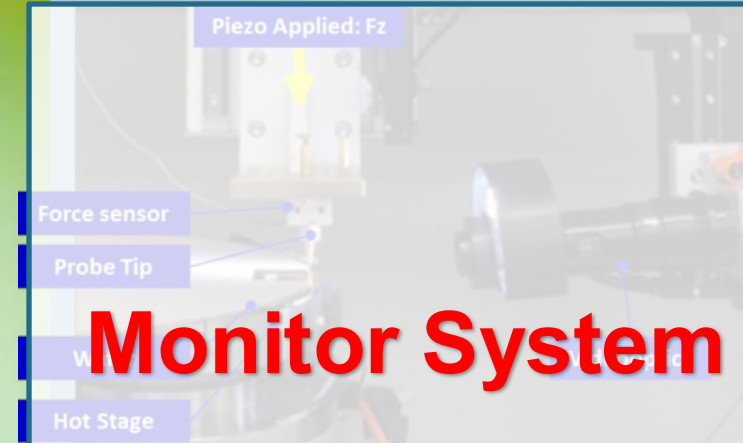


CRes
Unstable

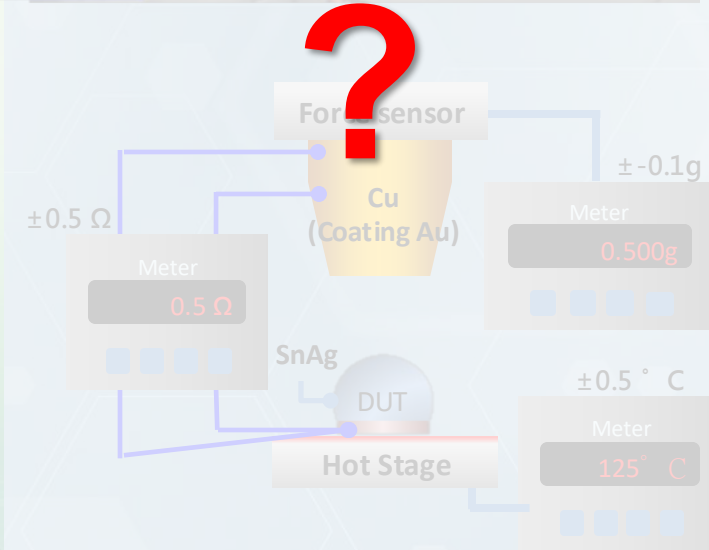
Available Range

Package issue

SWTest | June 5 - 7, 2023

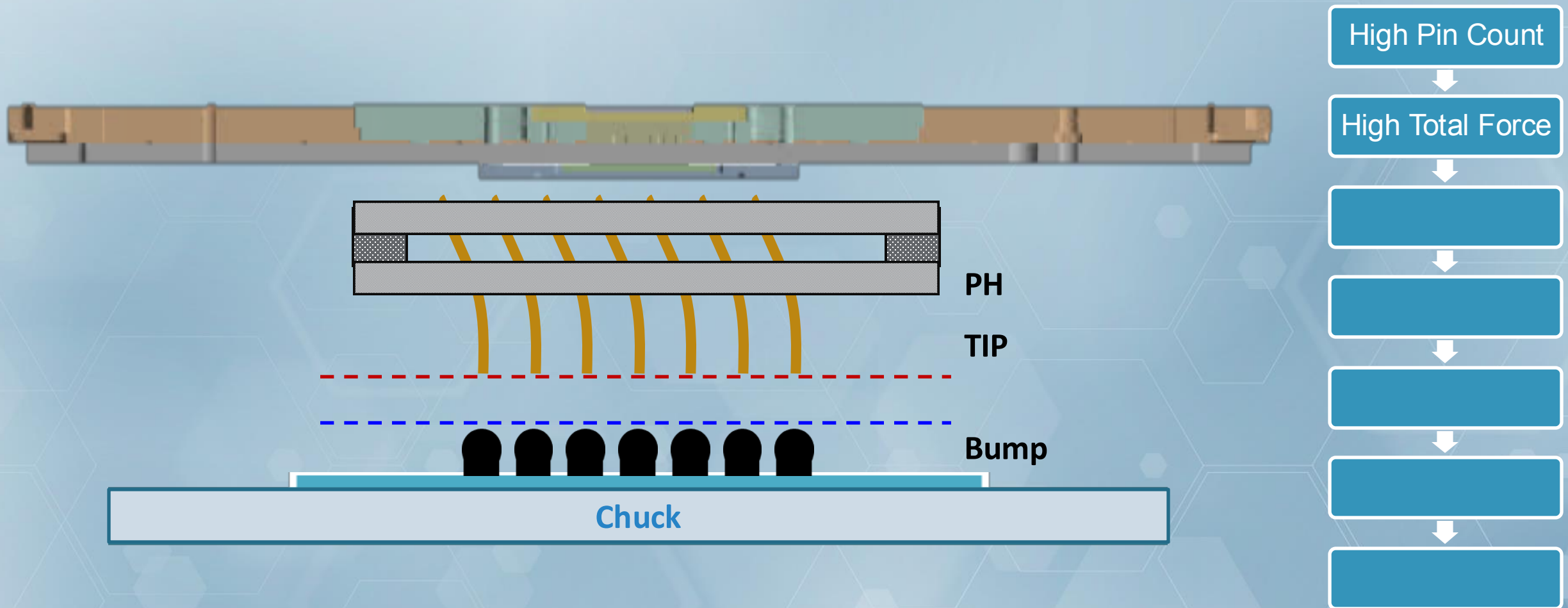


Monitor System



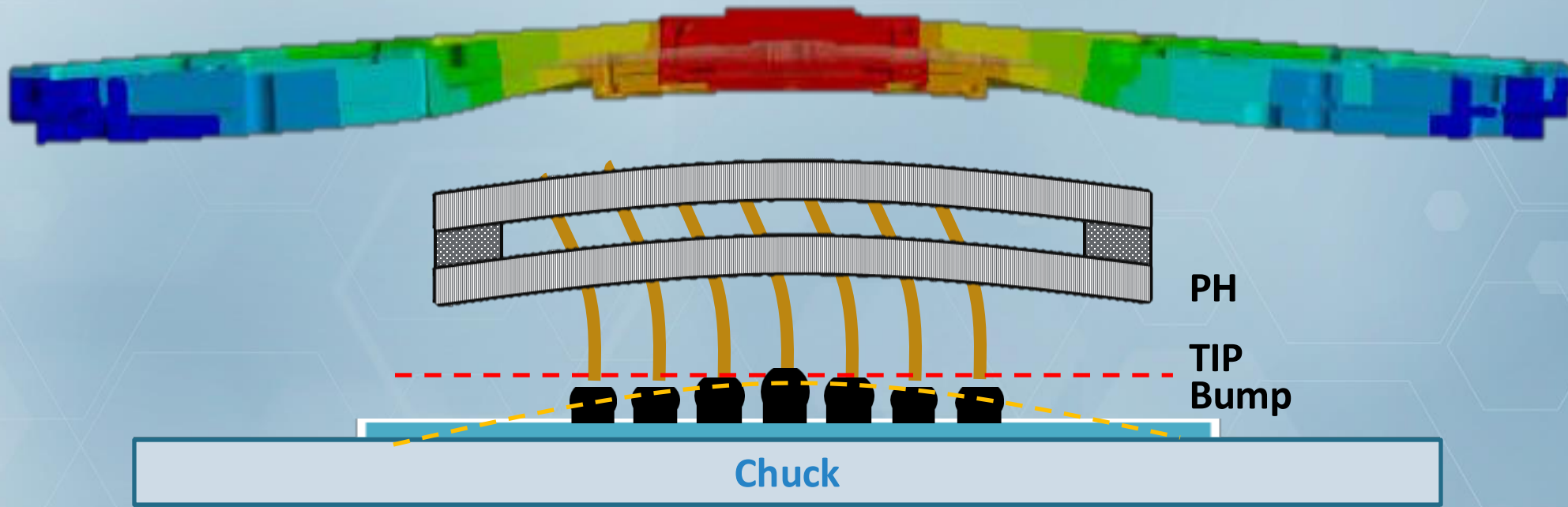
Why We need to know the Force Range of 100K+ Bump

For a high pin count card, a high force is generated. Initially, before testing, all levels are uniform.



Why We need to know the Force Range of 100K+ Bump

During testing, the entire card deforms under force, leading to inconsistencies between the inner and outer regions.



High Pin Count

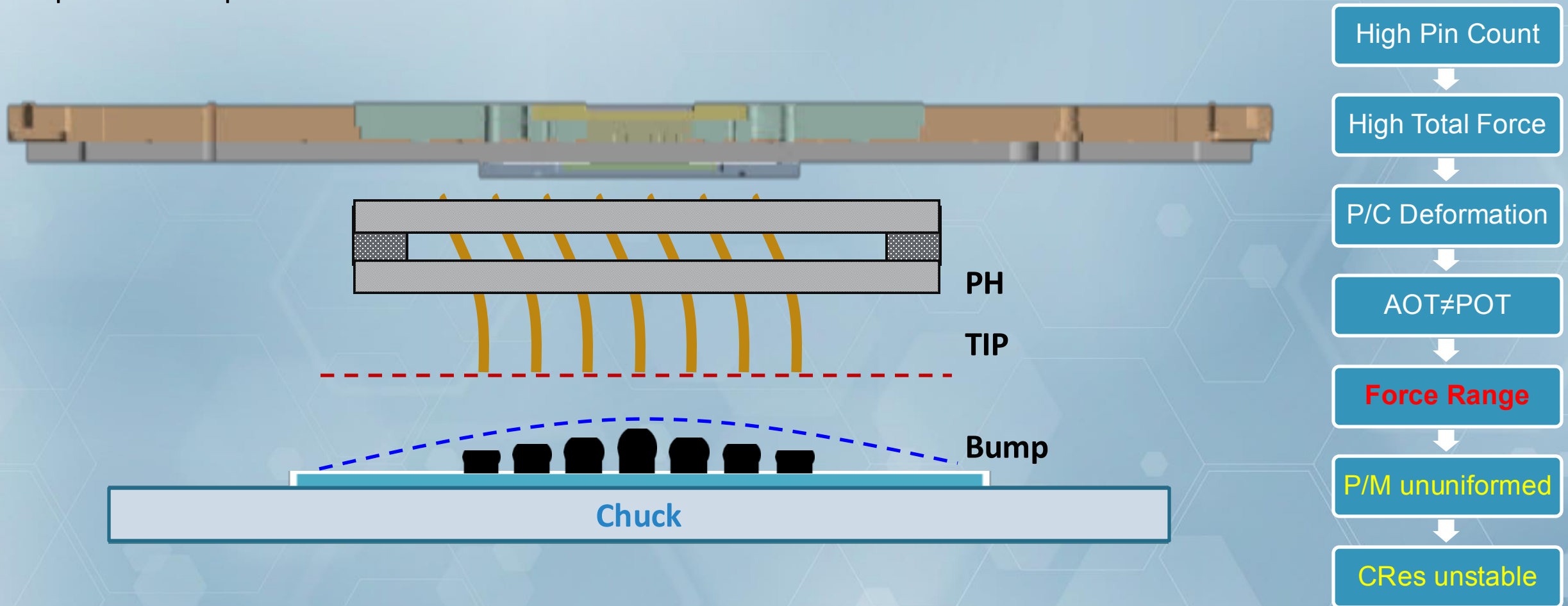
High Total Force

P/C Deformation

AOT≠POT

Why We need to know the Force Range of 100K+ Bump

The variation in AOT between the inner and outer regions causes a range of forces, leading to inconsistent probe mark performance and unstable contact resistance

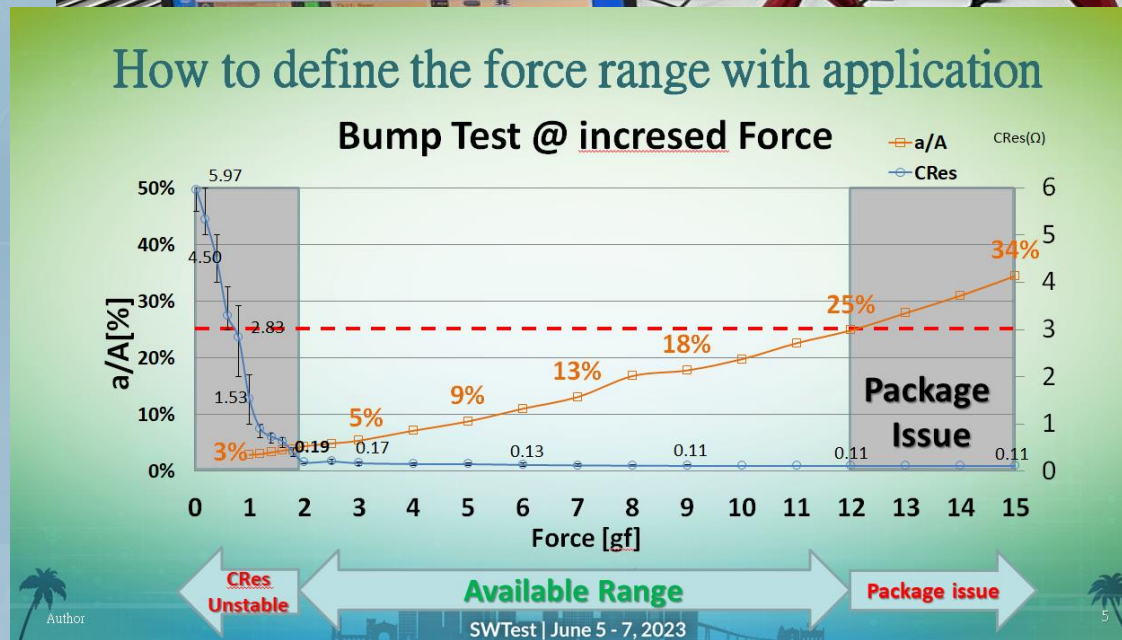


How We know the Force Range of 100K+ Bump



How We know the Force Range of 100K+ Bump

Deformation Monitored by Transducer



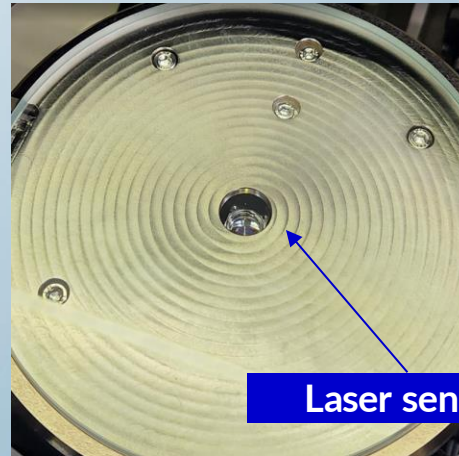
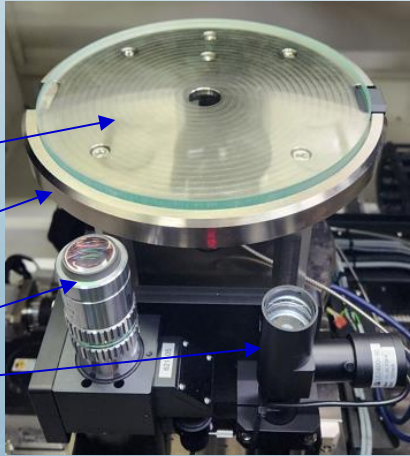
We Couldn't

Probe Card Level Monitor System

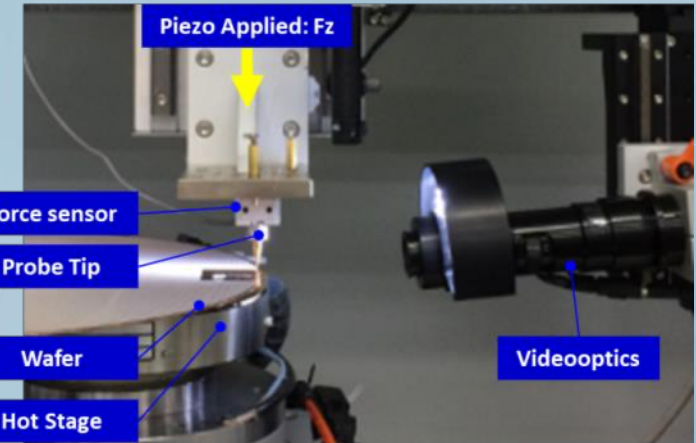
Transparent glass

Chuck

High-magnification
CCD
CCD



Laser sensor



Piezo Applied: Fz

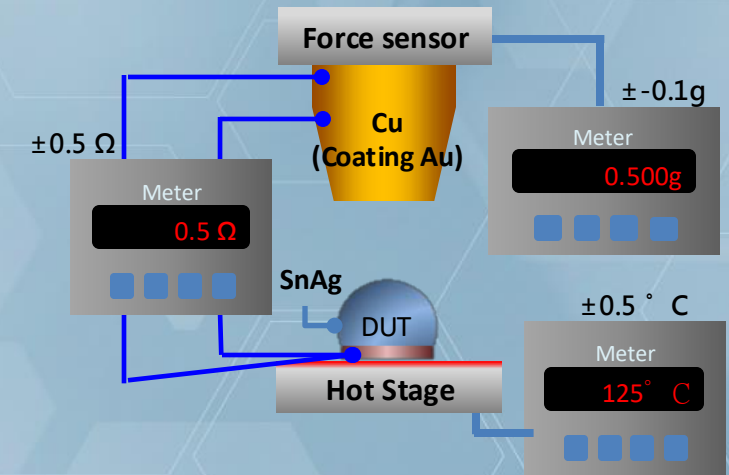
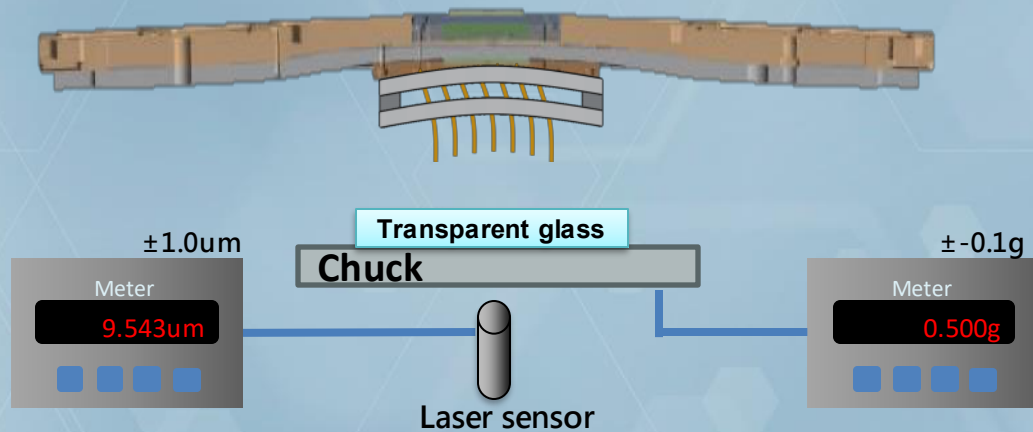
Force sensor

Probe Tip

Wafer

Hot Stage

Videooptics

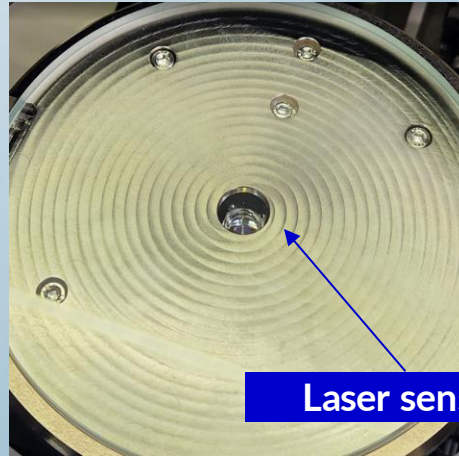
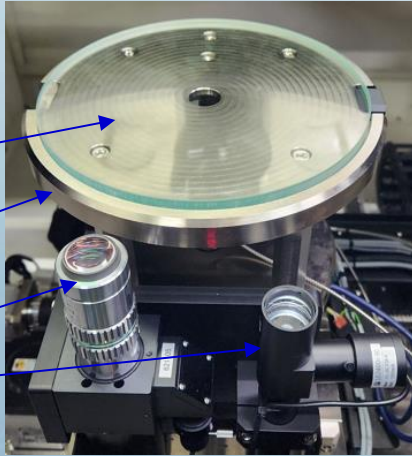


Probe Card Level Monitor System

Transparent glass

Chuck

High-magnification
CCD
CCD



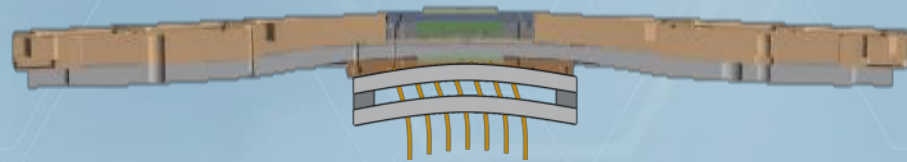
Laser sensor

$$Z_1 = Z_2$$

$$POT = AOT$$

$$Force_1 = Force_2$$

$$P/M_1 = P/M_2$$



$\pm 1.0\mu m$

Meter

9.543um

Transparent glass

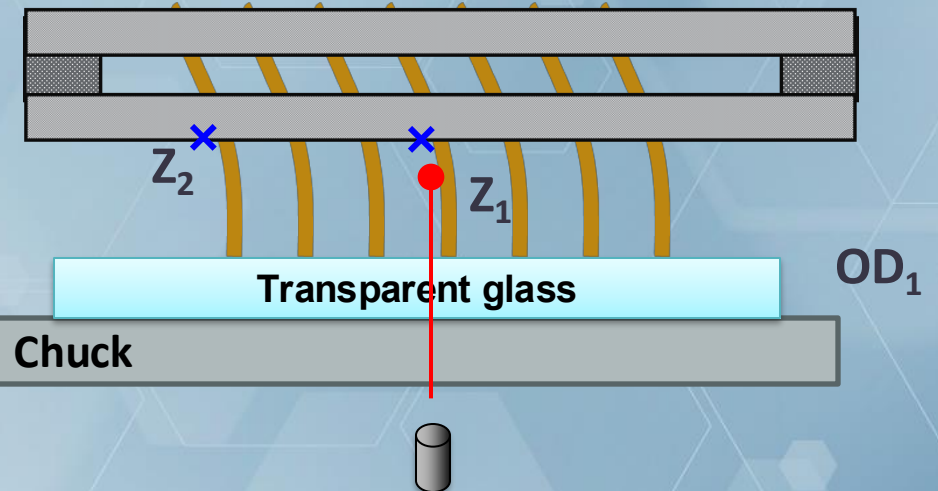
Chuck

$\pm 0.1g$

Meter

0.500g

Laser sensor

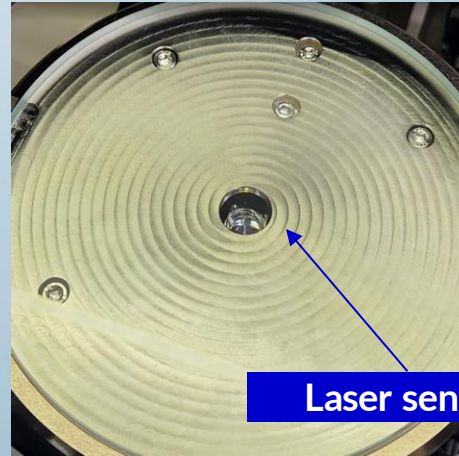
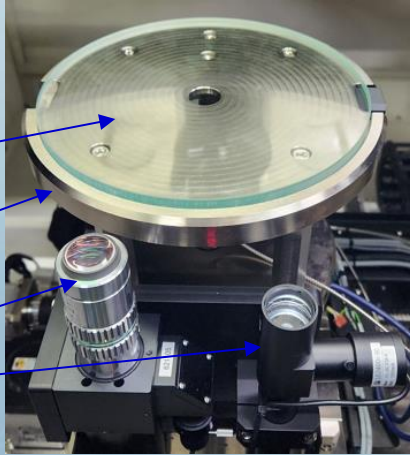


Probe Card Level Monitor System

Transparent glass

Chuck

High-magnification
CCD
CCD



Laser sensor

$$z_1 \neq z_2$$

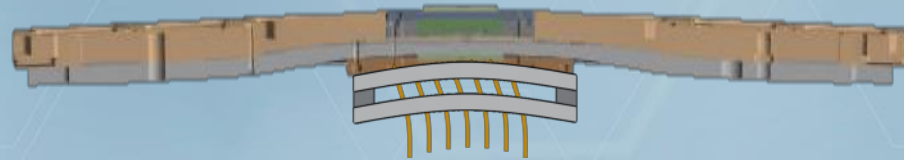
$$\text{POT} \neq \text{AOT}$$

$$\text{Force}_1 \neq \text{Force}_2$$

$$P/M_1 \neq P/M_2$$

$$\begin{aligned} \text{POT} - z_1 &= \text{AOT}_1 \\ \text{POT} - z_2 &= \text{AOT}_2 \end{aligned}$$

$$\text{CRes}_1 \neq \text{CRes}_2$$



$\pm 1.0\mu\text{m}$

Meter

9.543 μm

Transparent glass

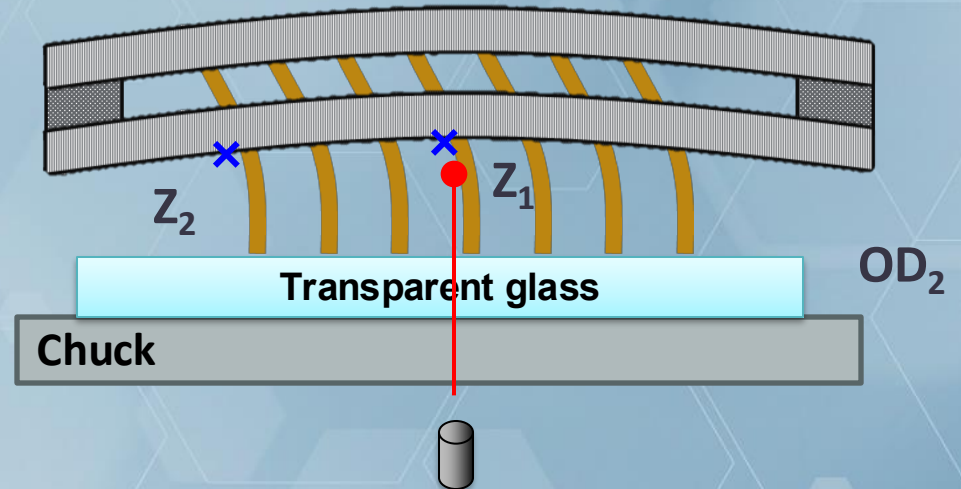
Chuck

Laser sensor

$\pm 0.1\text{g}$

Meter

0.500g



z_2

z_1

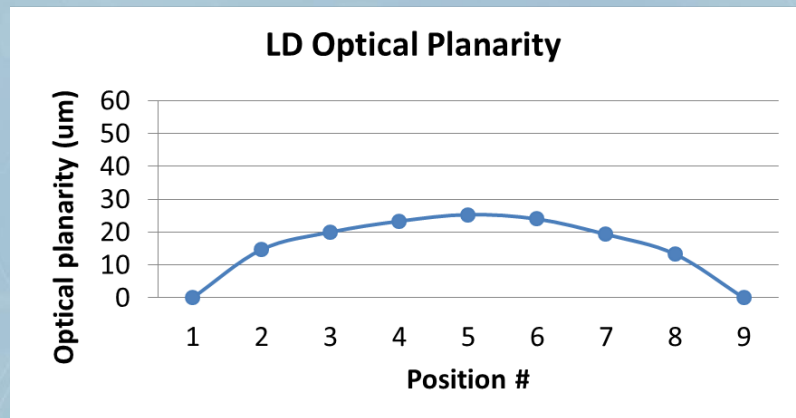
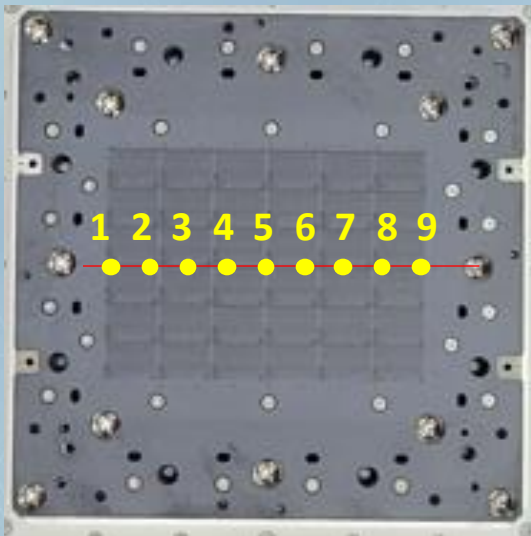
Transparent glass

Chuck

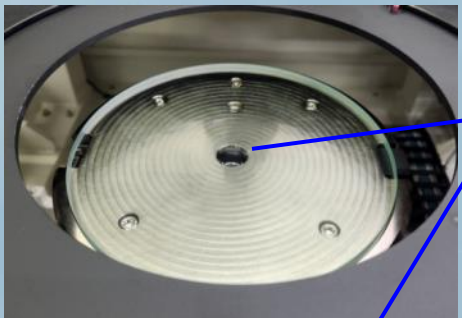
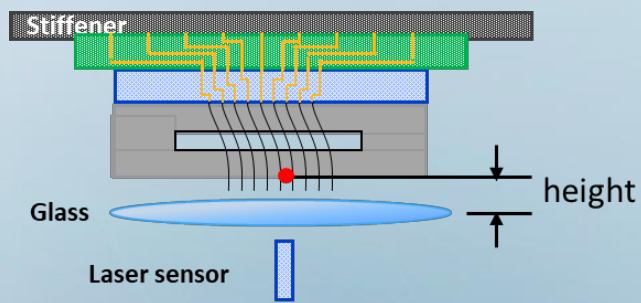
OD_2

P/C Force Measurement System

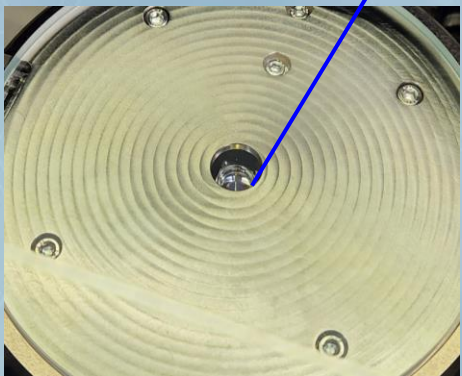
In order to better understand the relationship between the deformation of the entire card and probe mark performance, our PCF system incorporates a laser displacement sensor beneath the chuck. This design allows us to directly monitor the trend of LD deformation under loading conditions, providing real-time insight into the card's deformation behavior.



PC Force Measurement System (REAL TIME Recording)



Laser sensor



MPI

狀態MANUAL訊息[Alarm:40002](Aux:0)E_SYS_ALM_SYSTEM_INITIALIZE_FINISH

控制模式Remote產品Default

Time2024/09/26 15:25:49 (GMT+08:00)

User@BasicUI1.0.1.0

Auth.BasicSys1.00.01.00

8x20x測試值紀錄

Chuck移動 設定測試位置 測試頁面

DP 位置設定 設定20x測試位置 設定Chuck測試位置

位置設定 - Pad No.01

X(mm)	85.618
Y(mm)	-486.863
Z(mm)	17.872

設定清除

重置所有DP位置

相機切換

08x20x

下個 Pad

X軸位置 (mm)87.738

Y軸位置 (mm)-407.644

Z軸位置 (mm)17.869

Load Cell (μ)20.8

雷射測距 (mm)-24.0

Force display

Deformation display

平台XY軸

X	87.738	Y	-407.644
Offset	0.001	Offset	0.001

平台XY軸-寸動

X	87.73795	Y	-407.643
ΔX	0.00005	ΔY	0.00005

點測Z軸

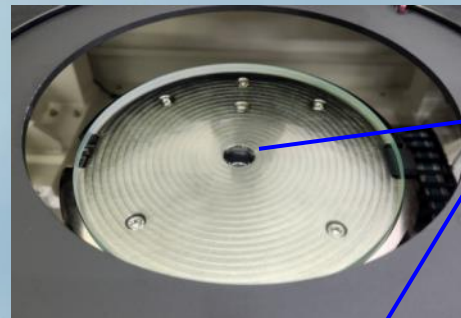
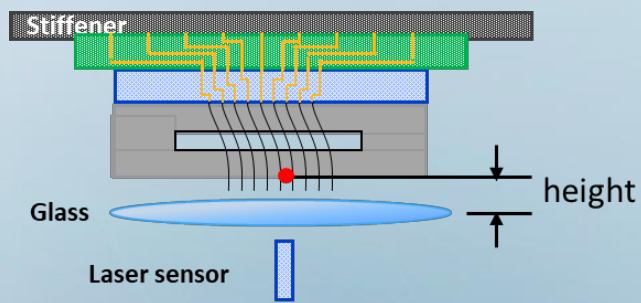
Pos	17.869
Move	1.000
Step	0.001
Jog	

初始化上卡介面使用者介面相對量介面

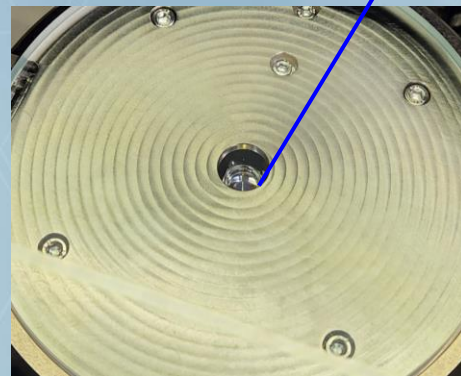
操作模式維護介面系統

PCF(M)READY FOR THE TEST™

PC Force Measurement System (REAL TIME Recording)



Laser sensor



MPI

狀態MANUAL訊息[Alarm:40002](Aux:0)E_SYS_ALM_SYSTEM_INITIALIZE_FINISH

控制模式Remote產品Default

Time2024/09/26 15:25:49 (GMT+08:00)

User@BasicUI1.0.1.0

Auth.BasicSys1.00.01.00

8x20x測試值紀錄

More

Chuck移動 設定測試位置 測試頁面

DP 位置設定 設定20x測試位置 設定Chuck測試位置

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X(mm)	85.618
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設定清除

重置所有DP位置

相機切換

08x20x

下個 Pad

X軸位置 (mm)87.738

Y軸位置 (mm)-407.644

Z軸位置 (mm)17.869

Load Cell (μ)20.8

雷射測量 (μm)-24.0

Force display

Deformation display

平台XY軸

平台XY軸-寸動

點測Z軸

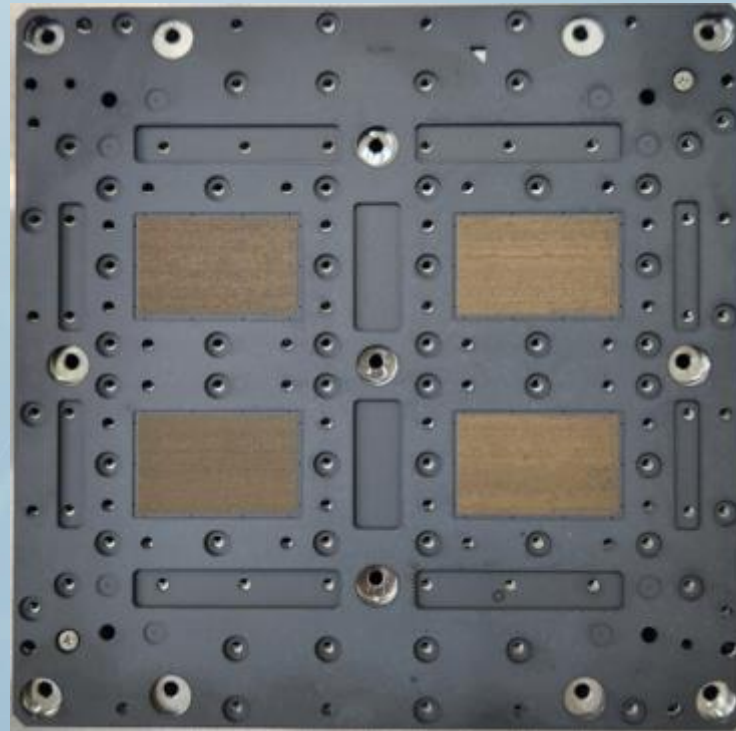
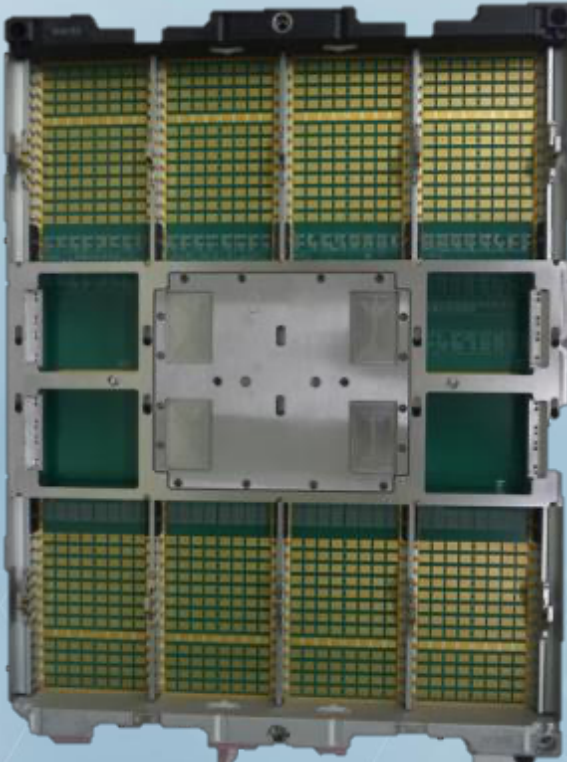
初始化上卡介面使用者介面相對量介面

操作模式維護介面系統

PCF(M) READY FOR THE TEST™

Example: Standard Card Types

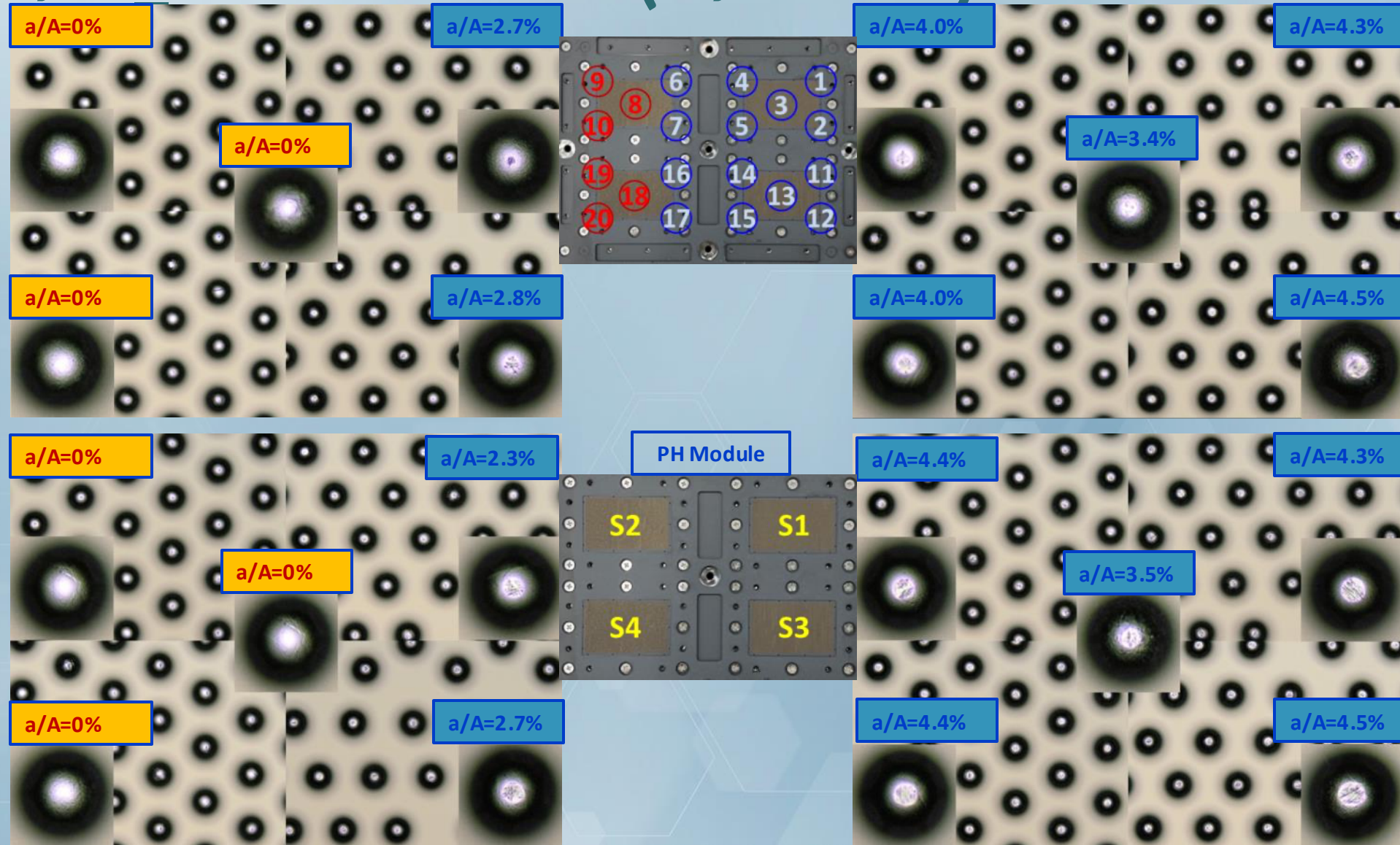
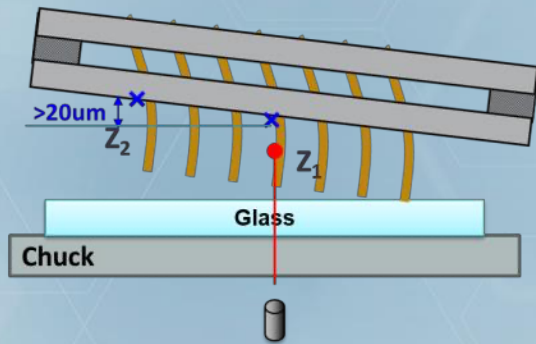
Standard Type with the following specifications:



- ✓ **PCB : DD FLEX PLUS (Larger)**
- ✓ **Pin Count : $\approx$ 100,000pins (2.5g per pin)**
- ✓ **Total force : 250kg (Ideally)**
- ✓ **Probing area : 78 x 51mm**
- ✓ **Needle Type: MEMS Needle**

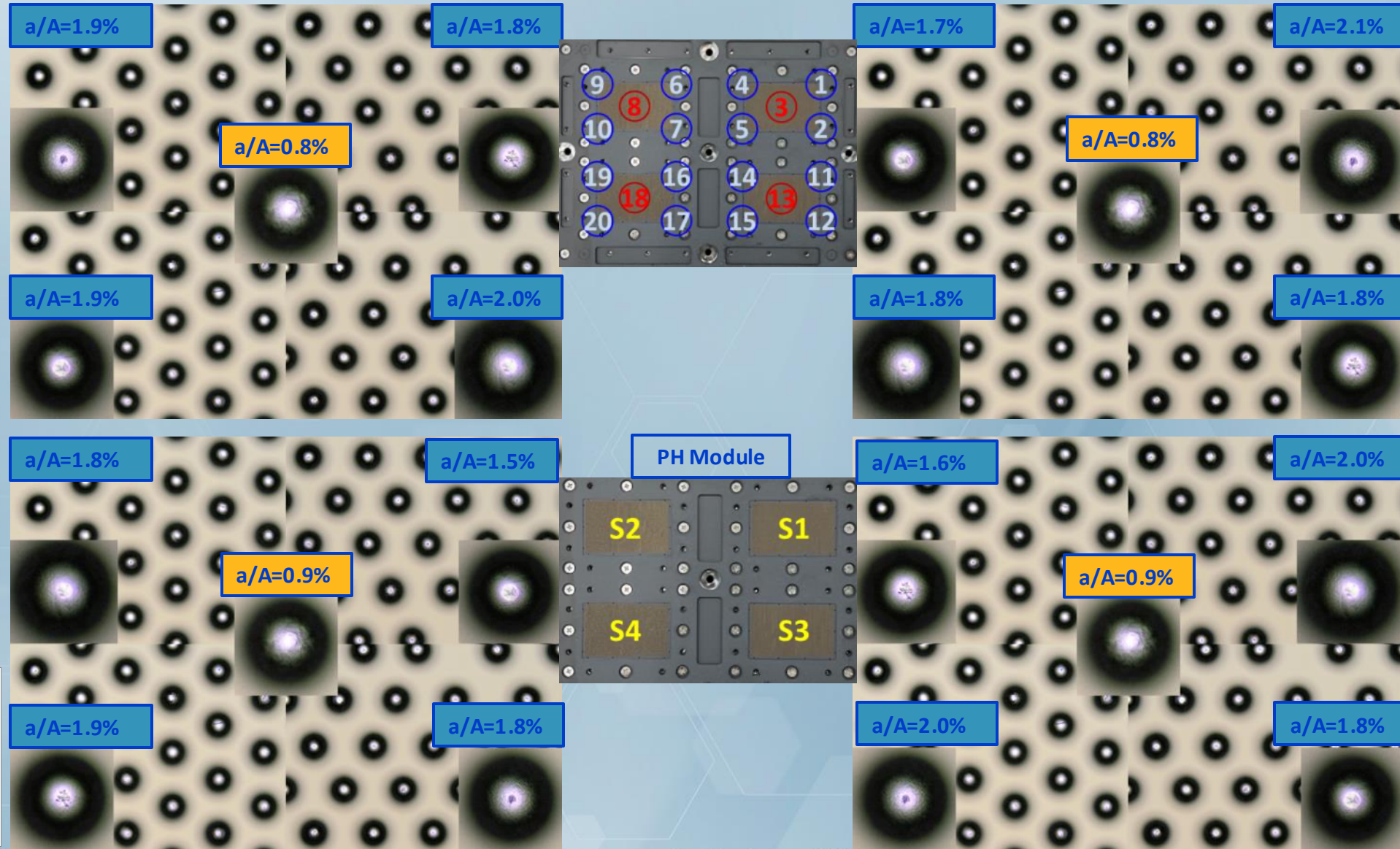
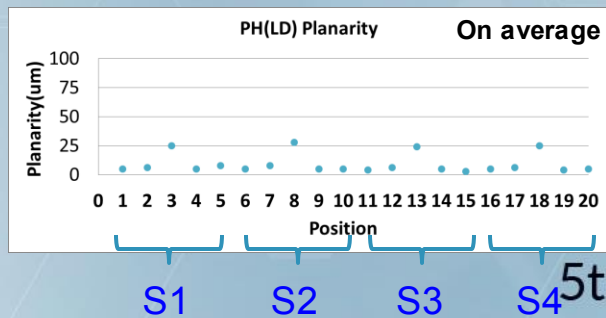
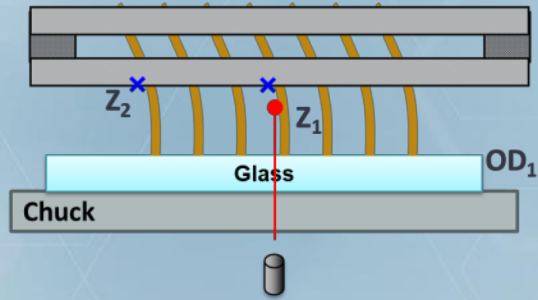
Standard P/C Probe mark (P/C Tilt)

- ✓ Bump : D80
- ✓ Pin Count : 100,000pins
(2.5g per pin)
- ✓ Probing area : 78 x 51mm



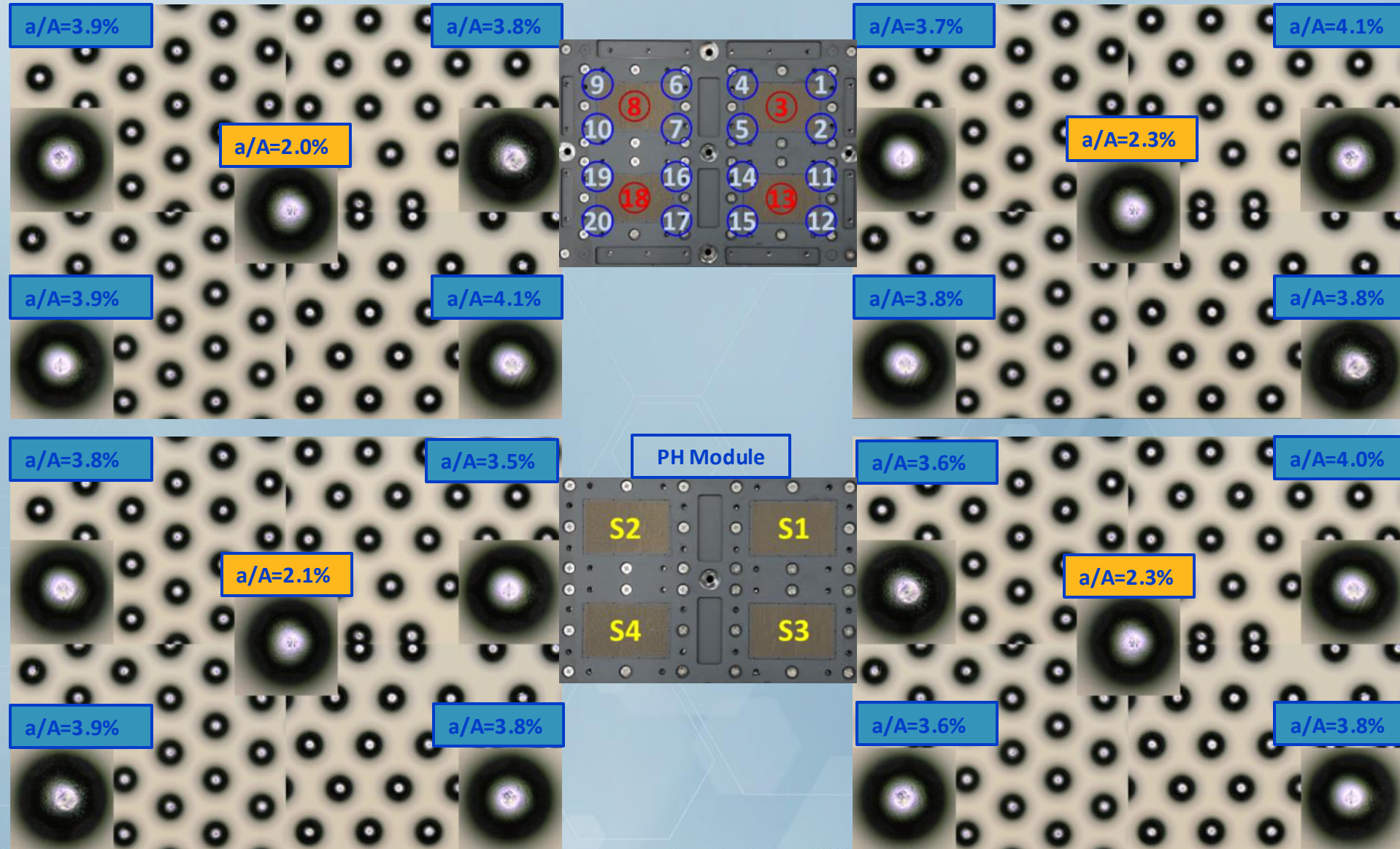
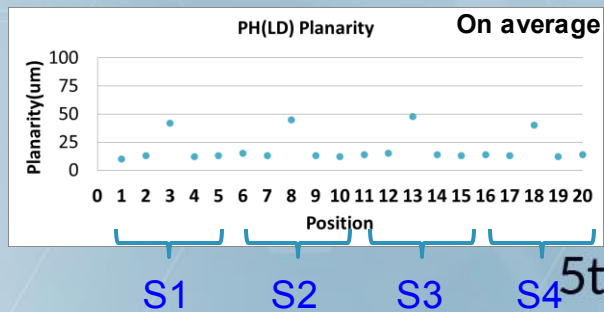
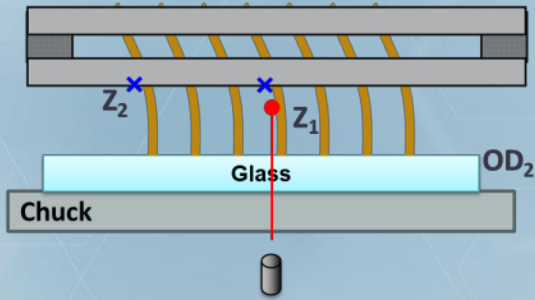
Standard P/C_Probe mark (POD50um)

- ✓ Bump : D80
- ✓ Pin Count : 100,000pins
(2.5g per pin)
- ✓ Probing area : 78 x 51mm
- ✓ Monitor point: 10 spot/area



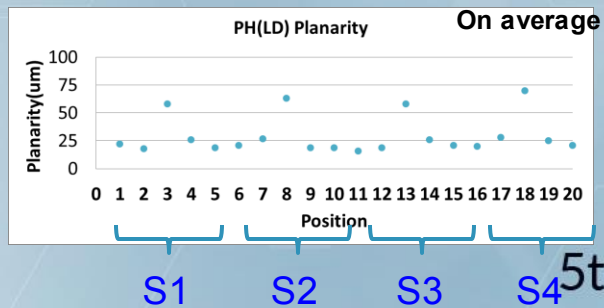
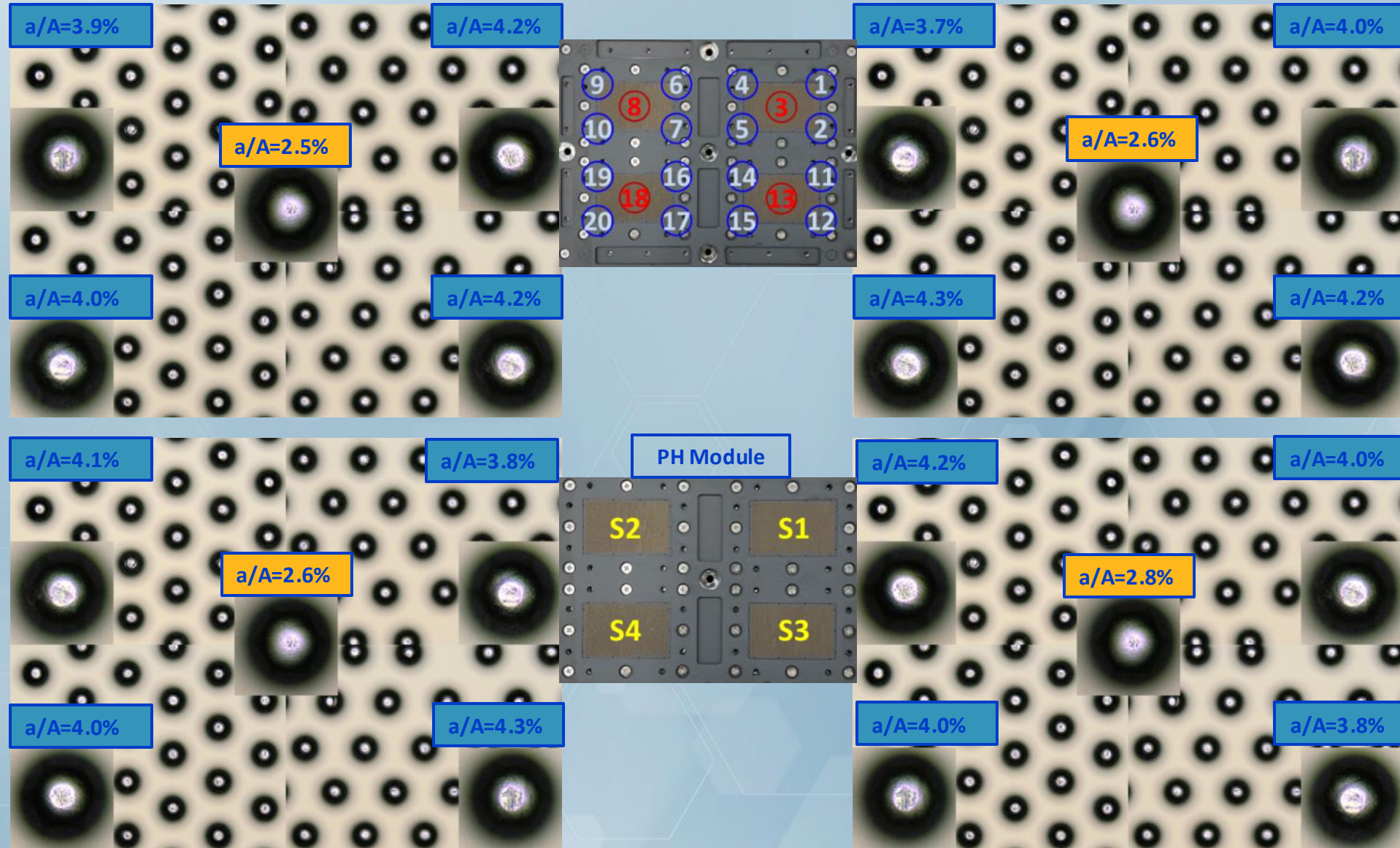
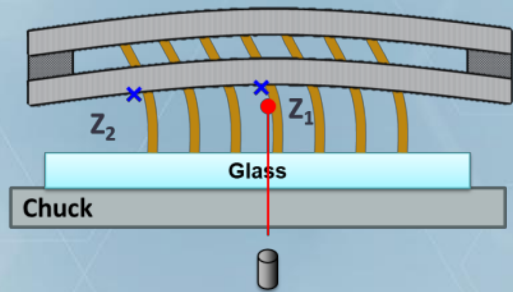
Standard P/C_Probe mark (POD75um)

- ✓ **Bump : D80**
- ✓ **Pin Count : 100,000pins**
(2.5g per pin)
- ✓ **Probing area : 78 x 51mm**
- ✓ **Monitor point: 10 spot/area**



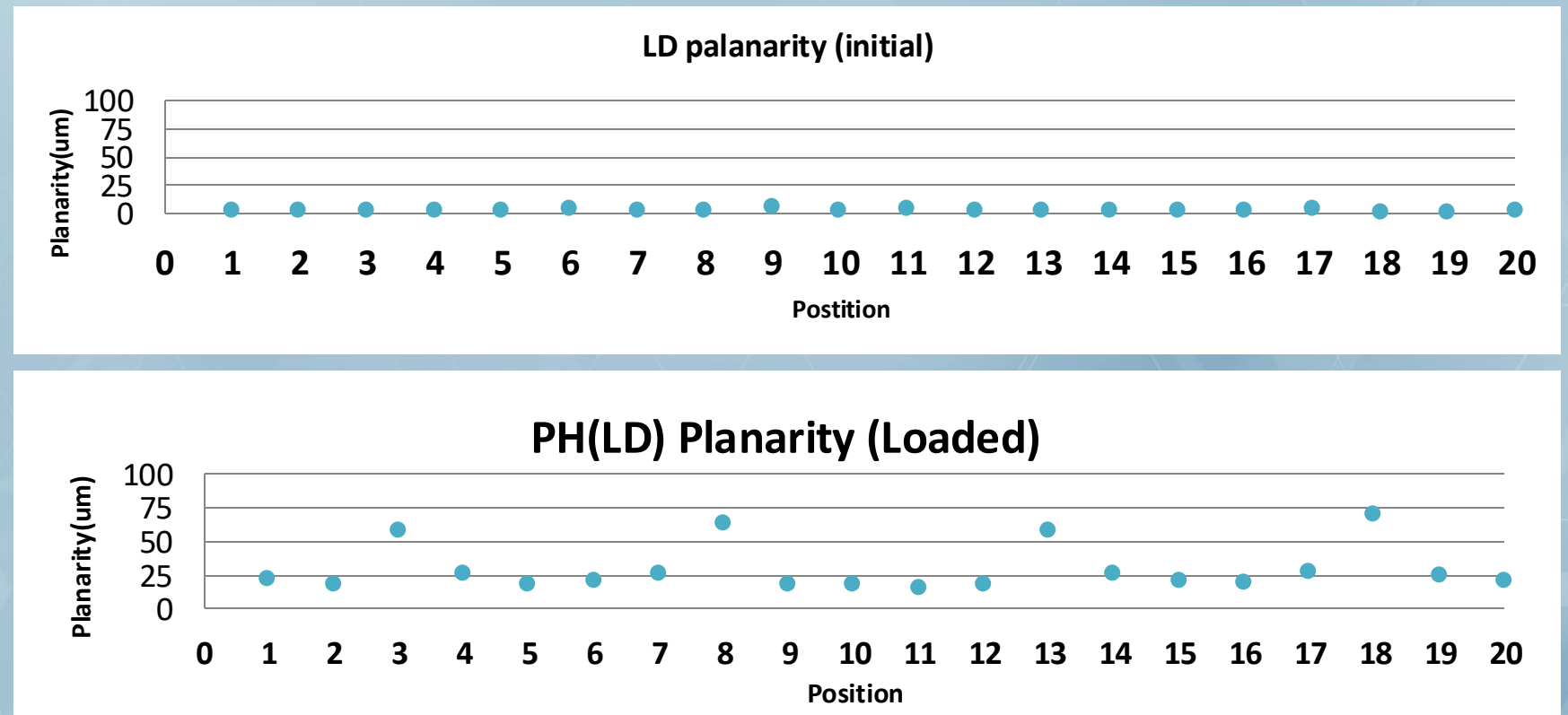
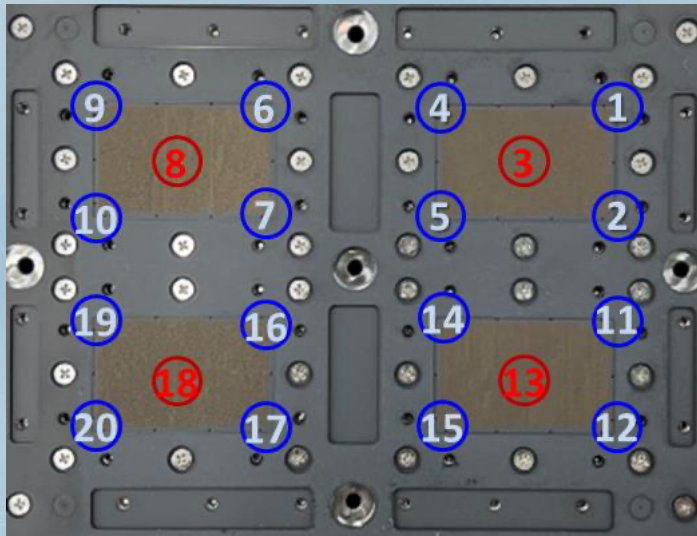
Standard P/C_Probe mark (POD100um)

- ✓ Bump : D80
- ✓ Pin Count : 100,000pins
(2.5g per pin)
- ✓ Probing area : 78 x 51mm
- ✓ Monitor point: 10 spot/area



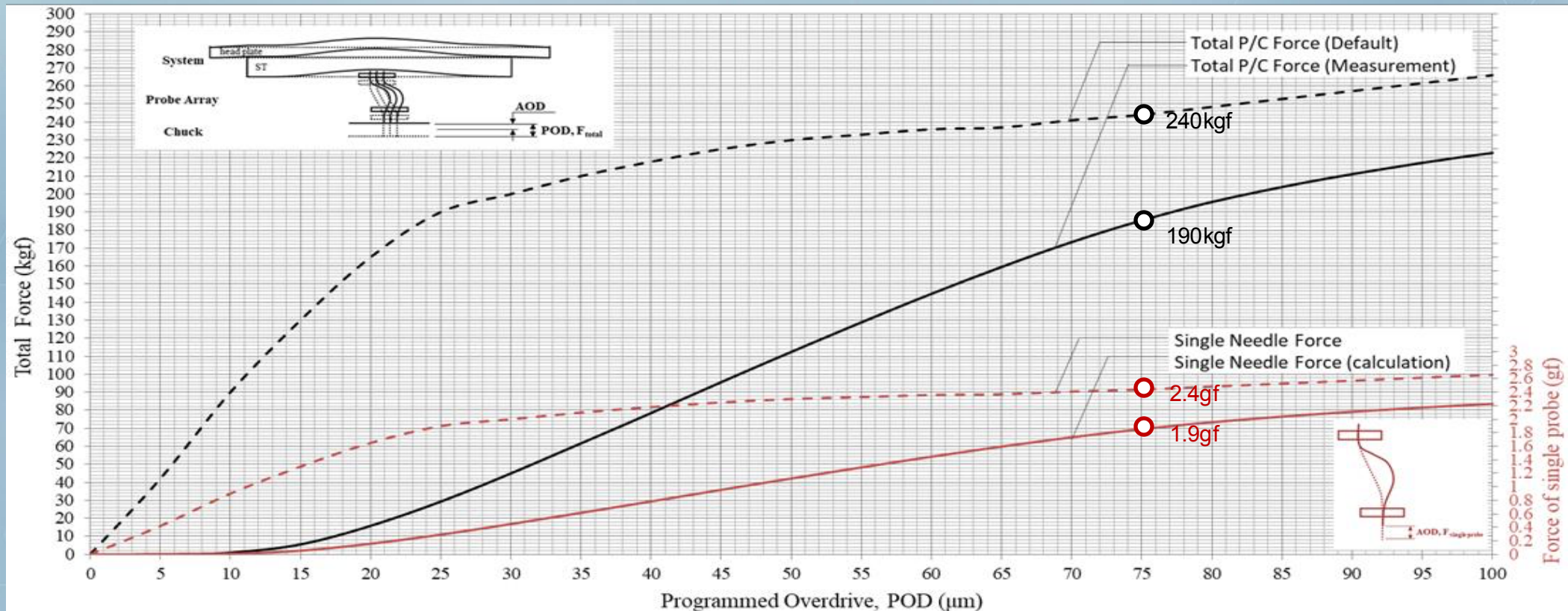
Standard P/C_LD Planarity

Under load, the deformation is most pronounced in the center of the layout.



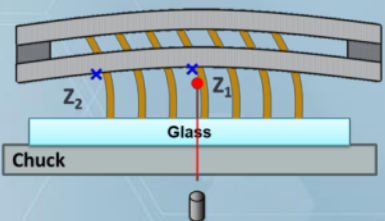
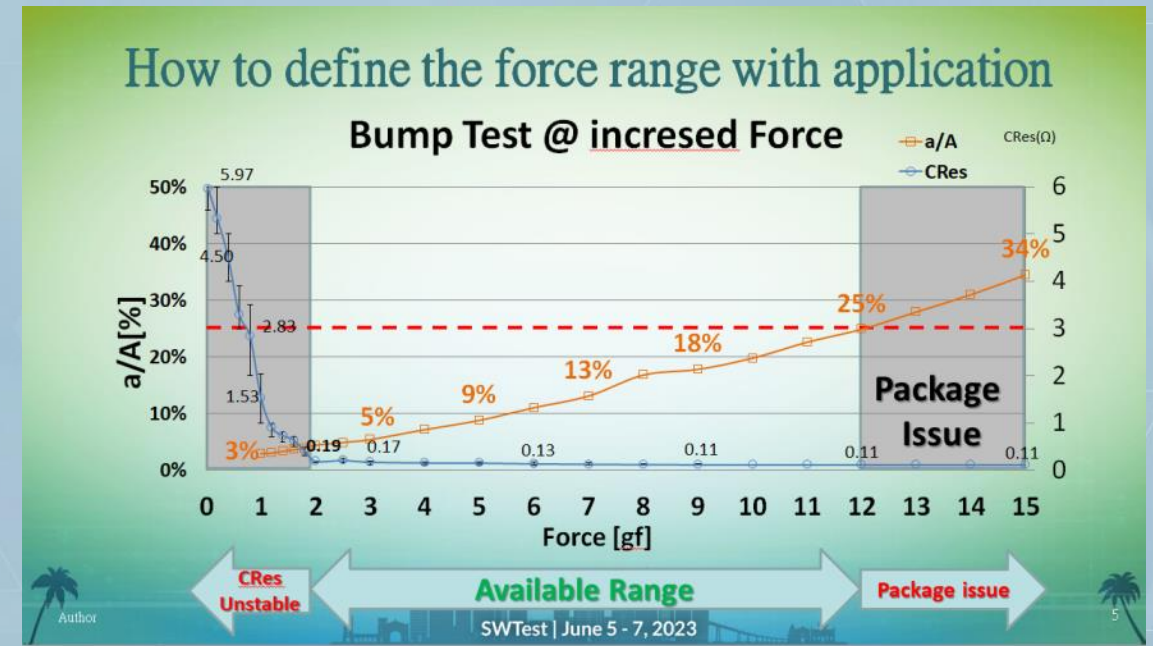
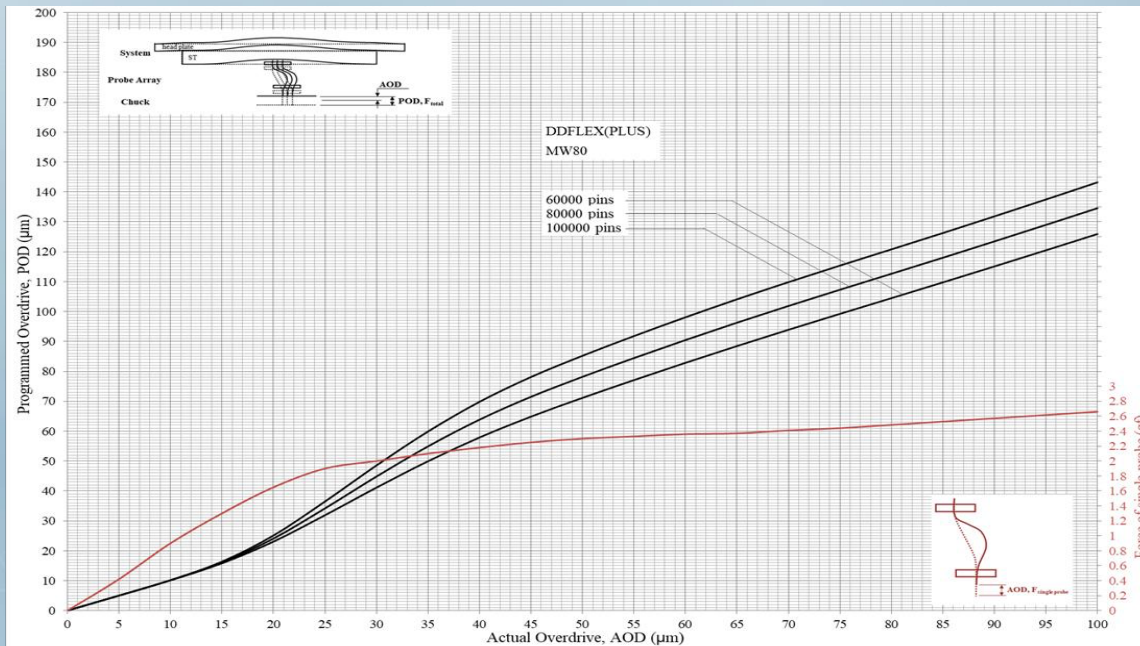
Standard P/C_ System Force and individual Force

The system force generated by the entire probe card calculated using the set values on prober will cause the force per individual pin to be much greater than the actual force per pin. This discrepancy is mainly because, after a certain overdrive, the probe card begins to deform, meaning that the overdrive of some individual pins is not sufficient in practice. As a result, the force per pin is also relatively weaker.



Multi-Bump Probe Mark Range Define

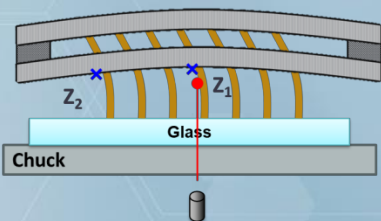
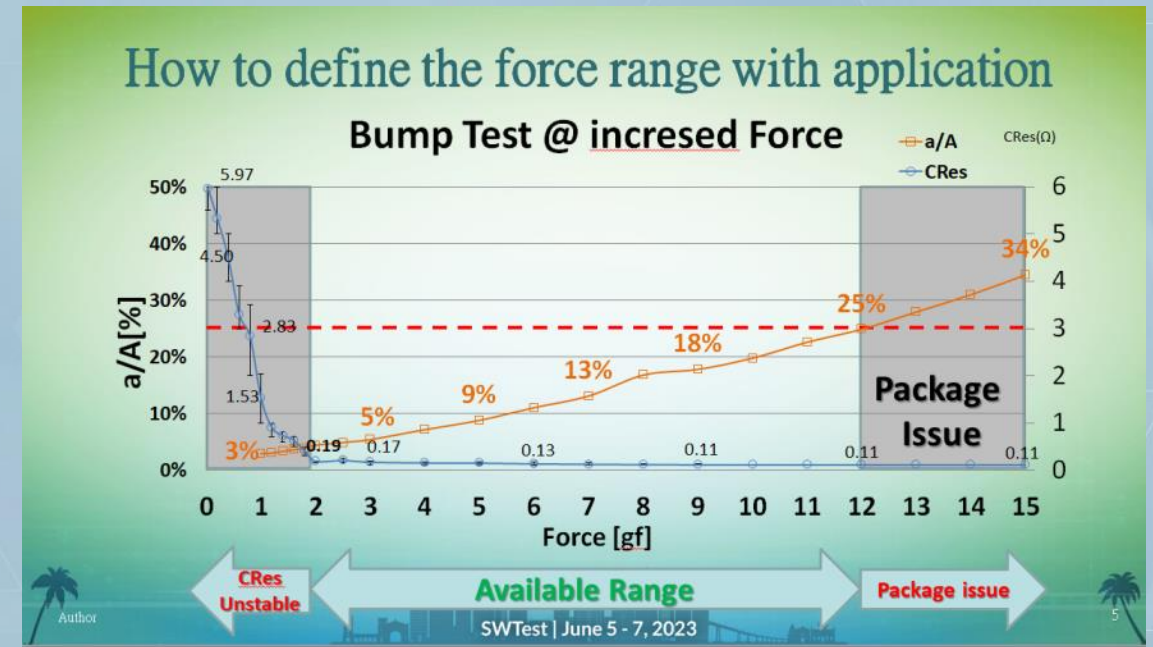
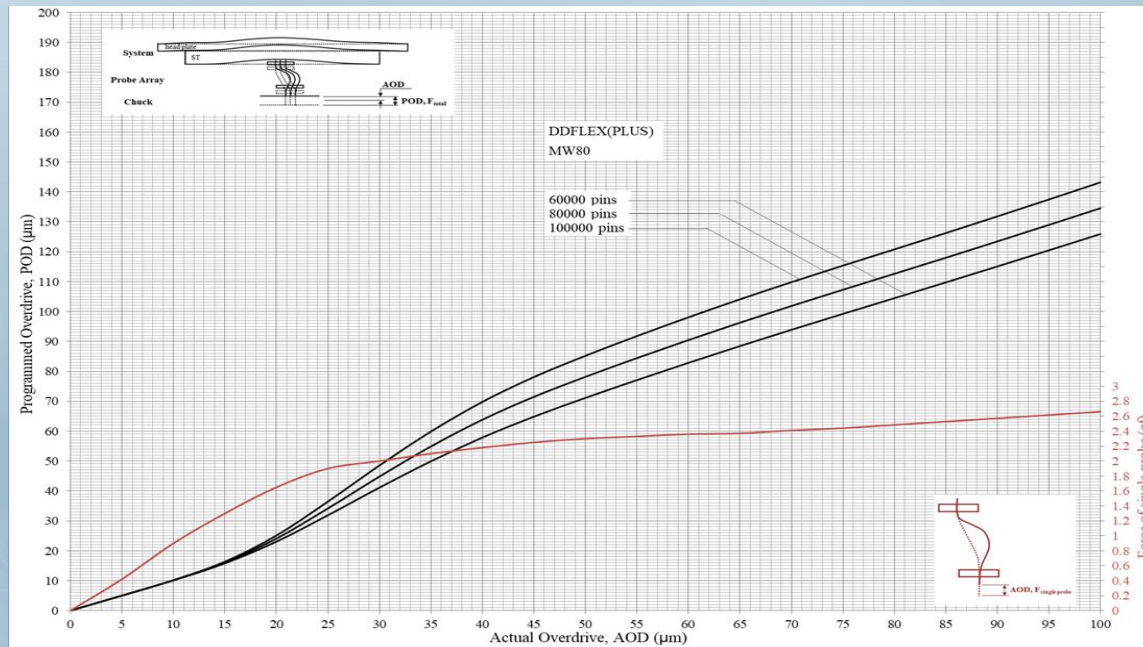
When the entire card deforms, the inner and outer areas experience different amounts of deformation, resulting in varying forces and different probe marks.



	POT	Deformation	AOT (Estimated)	Min Force (Estimated)	P/M a/A ratio (Estimated)
Z ₁	100	60~80	20	1.6 gf	3.2 %
Z ₂	100	10~30	70	2.4 gf	4.3 %

Multi-Bump Probe Mark Range Define for Real

When the entire card deforms, the inner and outer areas experience different amounts of deformation, resulting in varying forces and different probe marks.



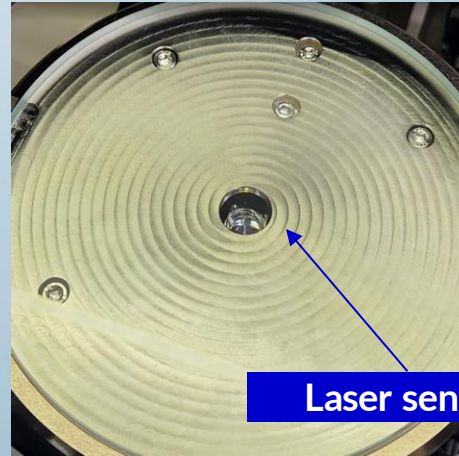
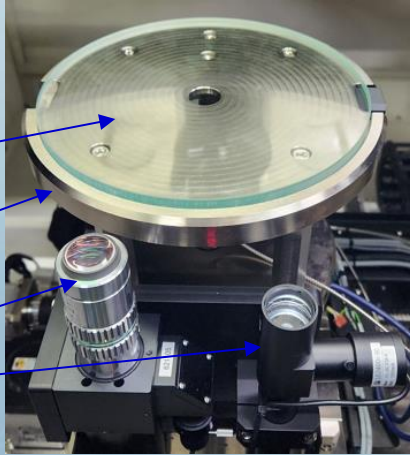
	POT	Deformation	AOT (Estimated)	Min Force (Estimated)	P/M a/A ratio (Estimated)	P/M a/A ratio (Measured)
Z_1	100	60~80	20	1.6 gf	3.2 %	2.6 %
Z_2	100	10~30	70	2.4 gf	4.3 %	4.0%

Probe Card Level Monitor System

Transparent glass

Chuck

High-magnification
CCD
CCD



Laser sensor

$$z_1 \neq z_2$$

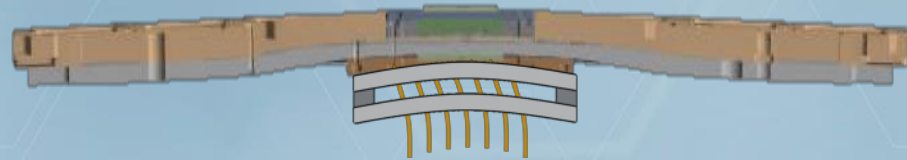
$$\text{POT} \neq \text{AOT}$$

$$\text{Force}_1 \neq \text{Force}_2$$

$$P/M_1 \neq P/M_2$$

$$\begin{aligned} \text{POT} - z_1 &= \text{AOT}_1 \\ \text{POT} - z_2 &= \text{AOT}_2 \end{aligned}$$

$$\text{CRes}_1 \neq \text{CRes}_2$$



$\pm 1.0\mu\text{m}$

Meter

9.543 μm

Transparent glass

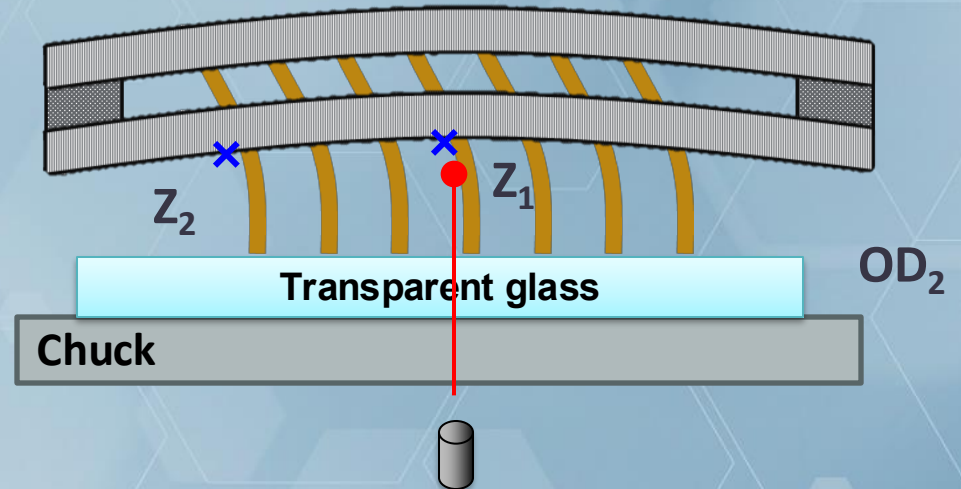
Chuck

Laser sensor

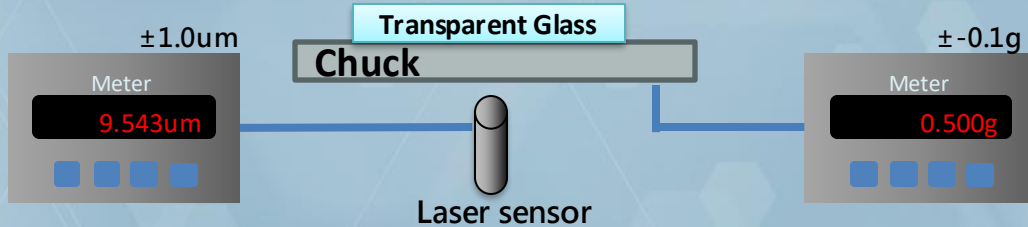
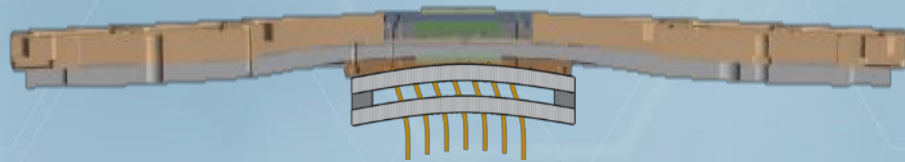
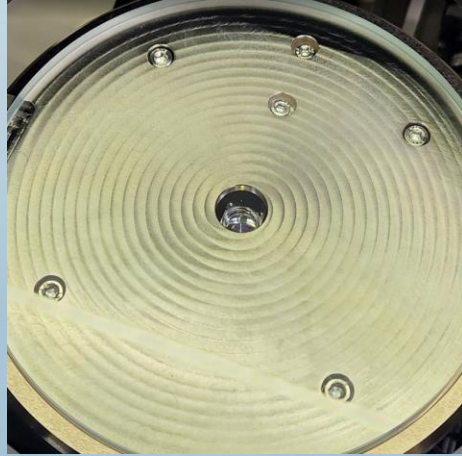
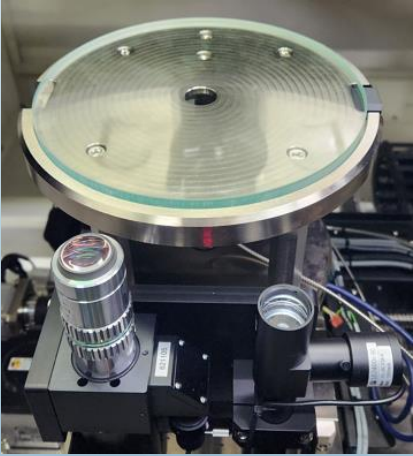
$\pm 0.1\text{g}$

Meter

0.500g

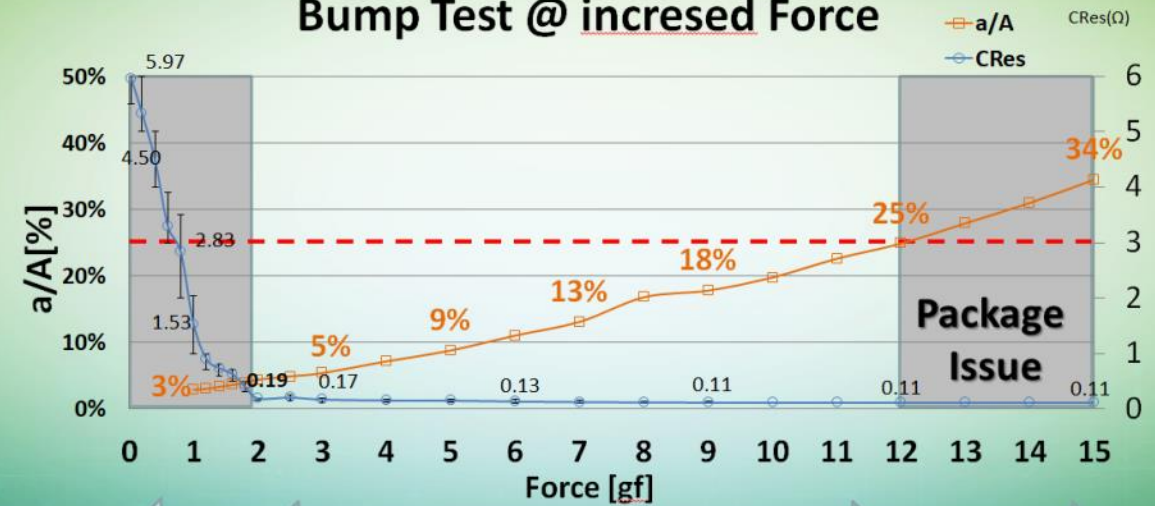


Probe Card Level Monitor System



How to define the force range with application

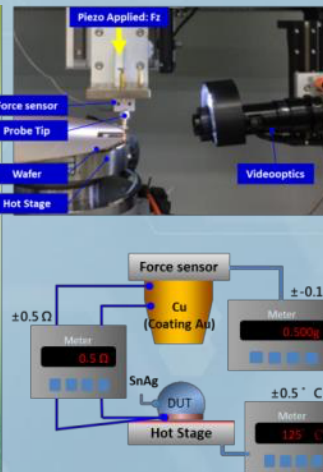
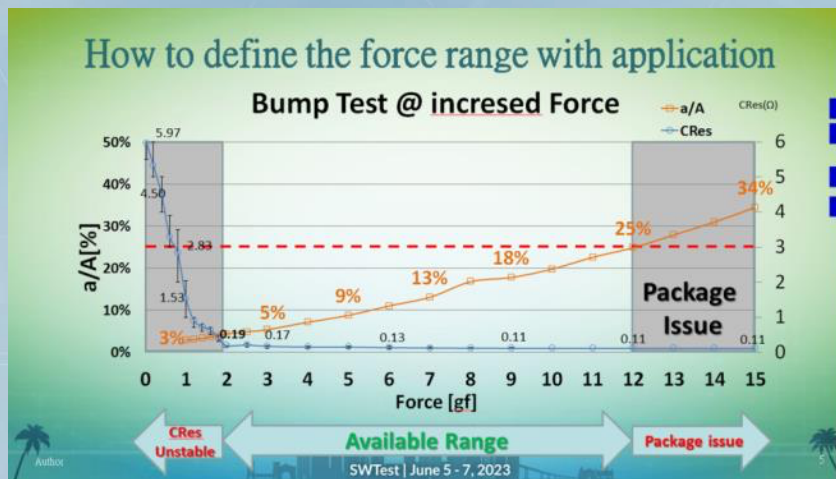
Bump Test @ increased Force



Measurement System Evaluation

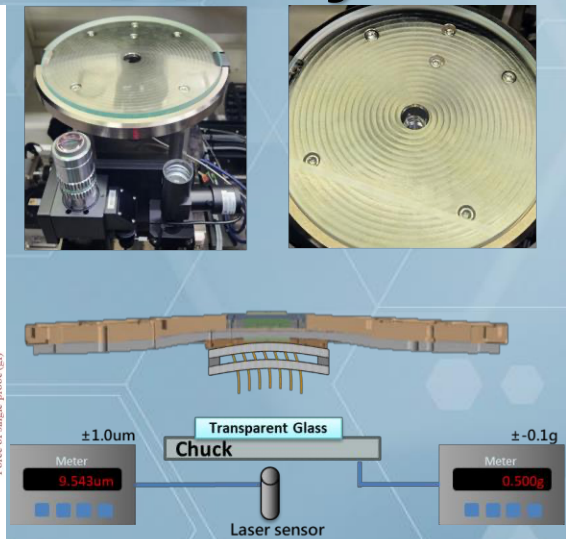
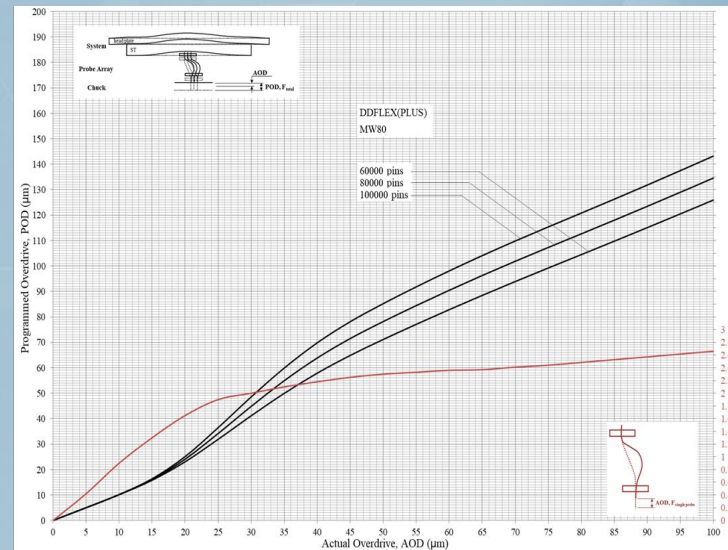
2023

Single Pin Measurement by Force Sensor



2024

Multi-Pin Measurement by Probe Card Force System



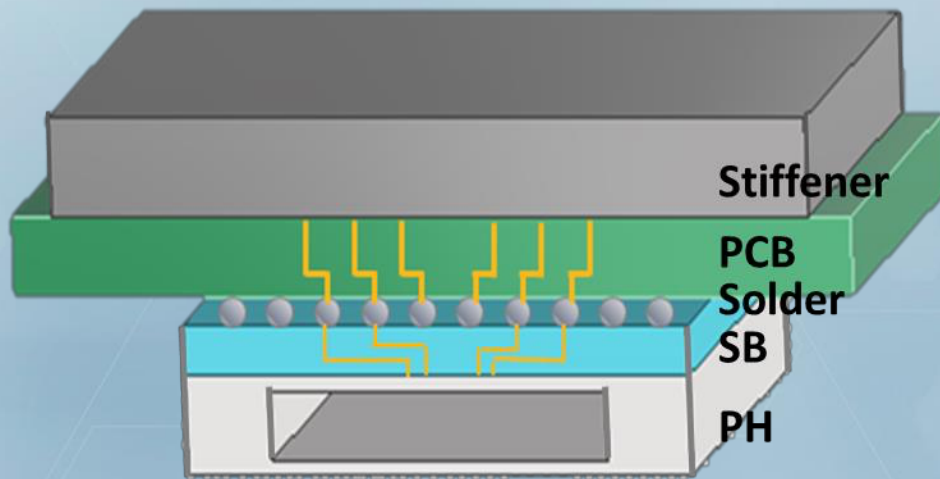
Summary

Conclusion:

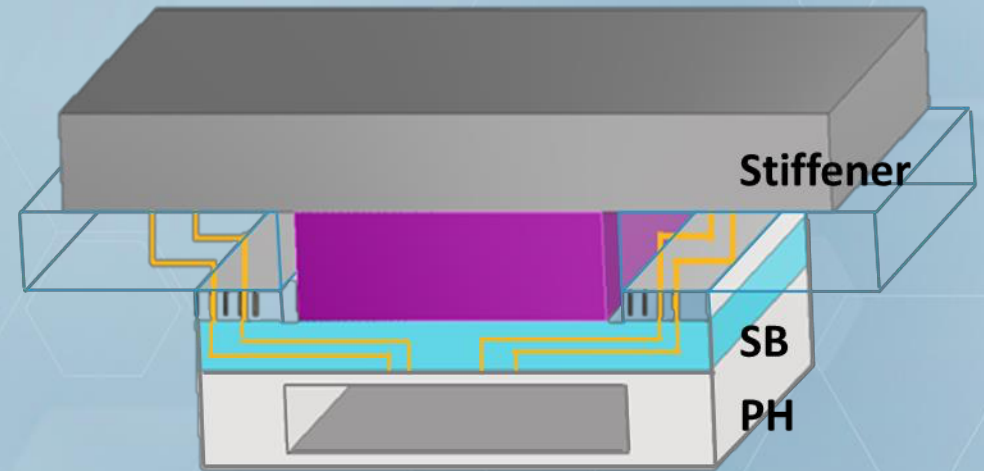
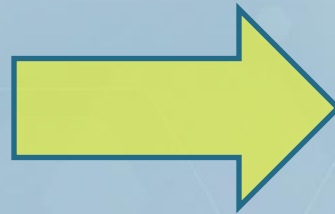
- ✓ High pin count generates greater force, leading to significant deformation. This causes varying deformation between the inner and outer regions of the entire card.
- ✓ With varying forces, the resulting probe marks differ, leading to non-uniformity in the probe mark patterns.
- ✓ The PCF system can monitor deformation in real-time, allowing for the estimation of the size of the probe marks.

Work in Future

- ✓ How can we prevent the occurrence of varying probe mark sizes?



Standard P/C



Next Generation P/C

- ✓ More Uniformed P/M
- ✓ More Stable CRes

Thank You